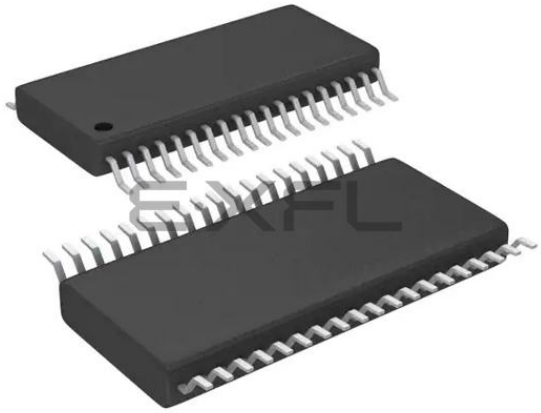

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc8662frabekxuma1

XC866 Data Sheet
Revision History: 2007-10 V1.2

Previous Version: V 0.1, 2005-01
V1.0, 2006-02
V1.1, 2006-12

Page	Subjects (major changes since last revision)
3	Device summary table is updated for Flash 4-Kb and ROM variants.
13	Footnote is added to MBC pin; description of V_{DDP} pin is updated.
25	Section on bit protection scheme and access type of register bit field PASSWD.PASS are updated.
26	Access type of PAGE bits of all module page registers are corrected to rwh.
29	Access type of Px_DIR register bits are corrected to rwh
38	New bullet point on Flash delivery state is added to the feature list.
88	Digital power supply voltage are differentiated for 5V and 3.3V variants.
89	New parameters on XTAL1 hysteresis and Voltage on GPIO pins during V_{DDP} power-off condition are added.
104	Figure on Power-on reset timing is updated.

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mcdocu.comments@infineon.com

Features (continued):

- Reset generation
  - Power-On reset
  - Hardware reset
  - Brownout reset for core logic supply
  - Watchdog timer reset
  - Power-Down Wake-up reset
- On-chip OSC and PLL for clock generation
  - PLL loss-of-lock detection
- Power saving modes
  - slow-down mode
  - idle mode
  - power-down mode with wake-up capability via RXD or EXINT0
  - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
  - 19 pins as digital I/O
  - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
  - Timer 0 and Timer 1 (T0 and T1)
  - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
  - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
  - 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range T_A:
  - SAF (-40 to 85 °C)
  - SAK (-40 to 125 °C)

Table 2 Device Summary

	SAK-XC866*-1FRI 3V	3.3	–	4	–	Industrial
	SAF-XC866*-4FRA 3V	3.3	12	4	–	Automotive
	SAF-XC866*-4FRI 3V	3.3	12	4	–	Industrial
	SAF-XC866*-2FRA 3V	3.3	4	4	–	Automotive
	SAF-XC866*-2FRI 3V	3.3	4	4	–	Industrial
	SAF-XC866*-1FRA 3V	3.3	–	4	–	Automotive
	SAF-XC866*-1FRI 3V	3.3	–	4	–	Industrial
ROM	SAK-XC866*-4RRA	5.0	–	4	16	Automotive
	SAK-XC866*-4RRI	5.0	–	4	16	Industrial
	SAK-XC866*-2RRA	5.0	–	4	8	Automotive
	SAK-XC866*-2RRI	5.0	–	4	8	Industrial
	SAF-XC866*-4RRA	5.0	–	4	16	Automotive
	SAF-XC866*-4RRI	5.0	–	4	16	Industrial
	SAF-XC866*-2RRA	5.0	–	4	8	Automotive
	SAF-XC866*-2RRI	5.0	–	4	8	Industrial
	SAK-XC866*-4RRA 3V	3.3	–	4	16	Automotive
	SAK-XC866*-4RRI 3V	3.3	–	4	16	Industrial
	SAK-XC866*-2RRA 3V	3.3	–	4	8	Automotive
	SAK-XC866*-2RRI 3V	3.3	–	4	8	Industrial
	SAF-XC866*-4RRA 3V	3.3	–	4	16	Automotive
	SAF-XC866*-4RRI 3V	3.3	–	4	16	Industrial
	SAF-XC866*-2RRA 3V	3.3	–	4	8	Automotive
	SAF-XC866*-2RRI 3V	3.3	–	4	8	Industrial

1) Industrial is not for Automotive usage

2) The flash memory (P-Flash and D-Flash) can be used for code or data.

*Note: The asterisk (*) above denotes the device configuration letters from **Table 1**.*

2.4 Pin Definitions and Functions

Table 3 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State	Function
P0		I/O		**Port 0** Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P0.0	12		Hi-Z	TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT Clock Output RXDO_1 UART Transmit Data Output
P0.1	14		Hi-Z	TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Data Input COUT61_1 Output of Capture/Compare channel 1 EXF2_1 Timer 2 External Flag Output
P0.2	13		PU	$\overline{\text{CTRAP}}$_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Data Output/ Clock Output
P0.3	2		Hi-Z	SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3
P0.4	3		Hi-Z	MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2
P0.5	4		Hi-Z	MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
V_{DDP}	18	–	–	**I/O Port Supply (3.3 V/5.0 V)** Also used by EVR and analog modules.
V_{SSP}	19	–	–	**I/O Port Ground**
V_{DDC}	8	–	–	**Core Supply Monitor (2.5 V)**
V_{SSC}	7	–	–	**Core Supply Ground**
V_{AREF}	25	–	–	**ADC Reference Voltage**
V_{AGND}	24	–	–	**ADC Reference Ground**
XTAL1	6	I	Hi-Z	**External Oscillator Input** **(NC if not needed)**
XTAL2	5	O	Hi-Z	**External Oscillator Output** **(NC if not needed)**
TMS	11	I	PD	**Test Mode Select**
$\overline{\text{RESET}}$	38	I	PU	**Reset Input**
MBC[1)]	1	I	PU	**Monitor & BootStrap Loader Control**

1) An external pull-up device in the range of 4.7 kΩ to 100 kΩ is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.

3.2 Memory Organization

The XC866 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM program memory
- 256 bytes of internal RAM data memory
- 512 bytes of XRAM memory
  (XRAM can be read/written as program memory or external data memory)
- a 128-byte Special Function Register area
- 4/8/16 Kbytes of Flash program memory (Flash devices); or
  8/16 Kbytes of ROM program memory, with additional 4 Kbytes of Flash
  (ROM devices)

Figure 6 illustrates the memory address spaces of the XC866-4FR device.

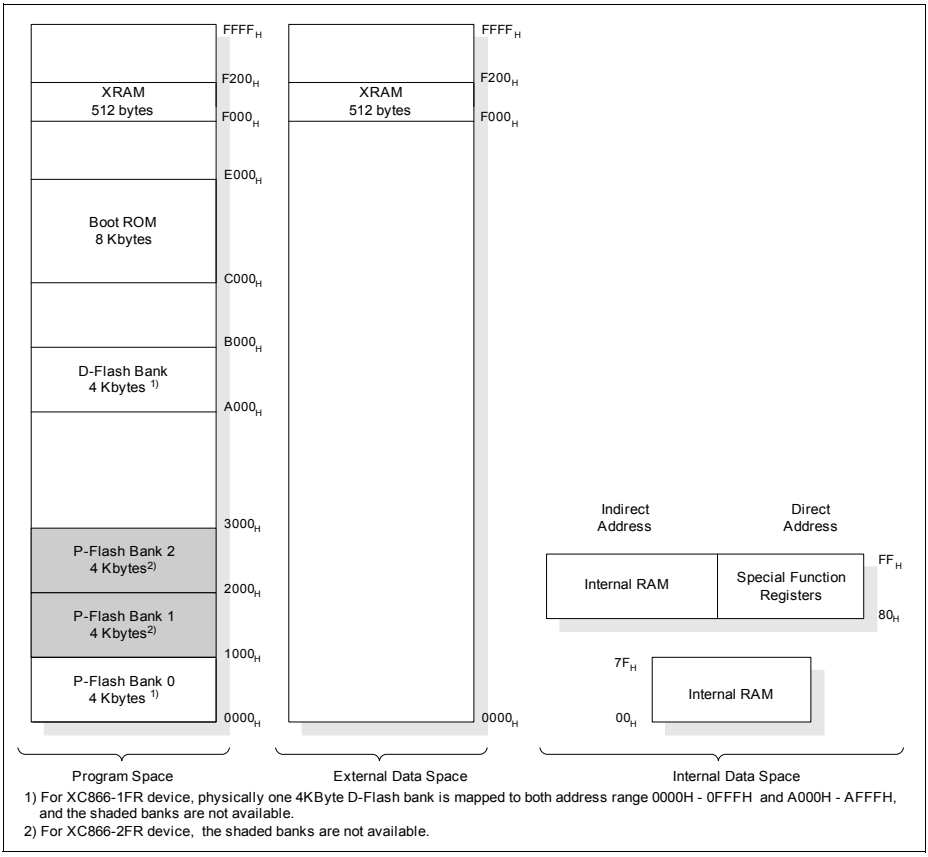
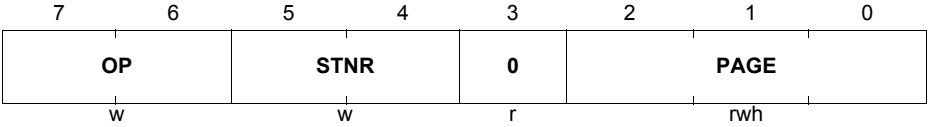


Figure 6 Memory Map of XC866 Flash Devices

The page register has the following definition:

MOD_PAGE
Page Register for module MOD **Reset Value: 00_H**



Field	Bits	Type	Description
PAGE	[2:0]	rwh	**Page Bits** When written, the value indicates the new page. When read, the value indicates the currently active page.
STNR	[5:4]	w	**Storage Number** This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10_B, the contents of PAGE are saved in STx before being overwritten with the new value. If OP = 11_B, the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored. 00 ST0 is selected. 01 ST1 is selected. 10 ST2 is selected. 11 ST3 is selected.

3.4 Interrupt System

The XC800 Core supports one non-maskable interrupt (NMI) and 14 maskable interrupt requests. In addition to the standard interrupt functions supported by the core, e.g., configurable interrupt priority and interrupt masking, the XC866 interrupt system provides extended interrupt support capabilities such as the mapping of each interrupt vector to several interrupt sources to increase the number of interrupt sources supported, and additional status registers for detecting and determining the interrupt source.

3.4.1 Interrupt Source

Figure 13 to **Figure 17** give a general overview of the interrupt sources and illustrates the request and control flags.

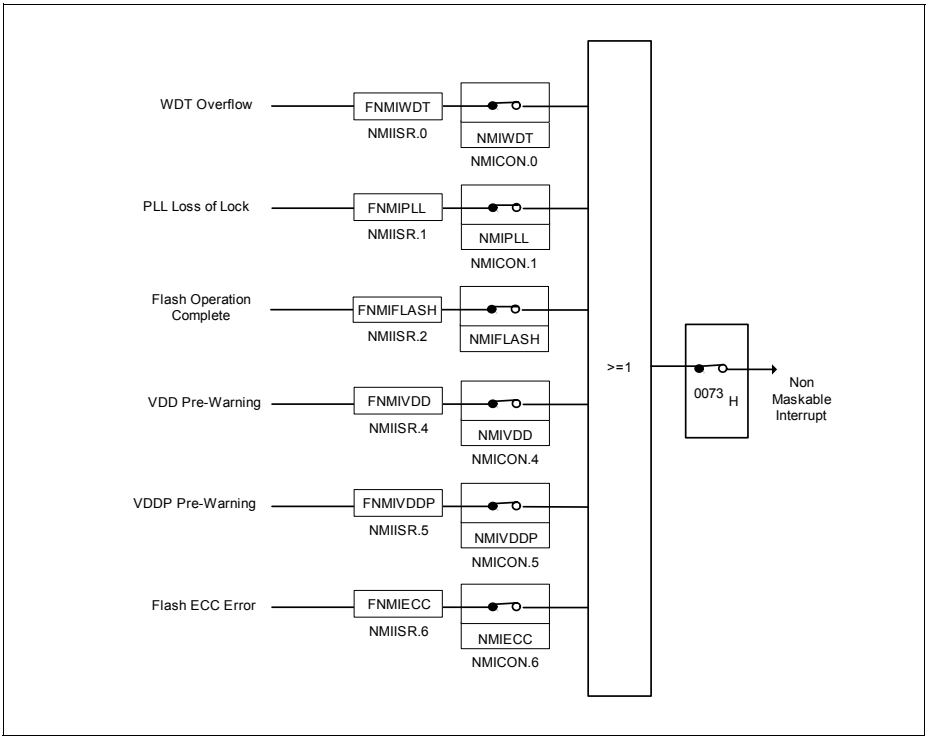


Figure 13 Non-Maskable Interrupt Request Sources

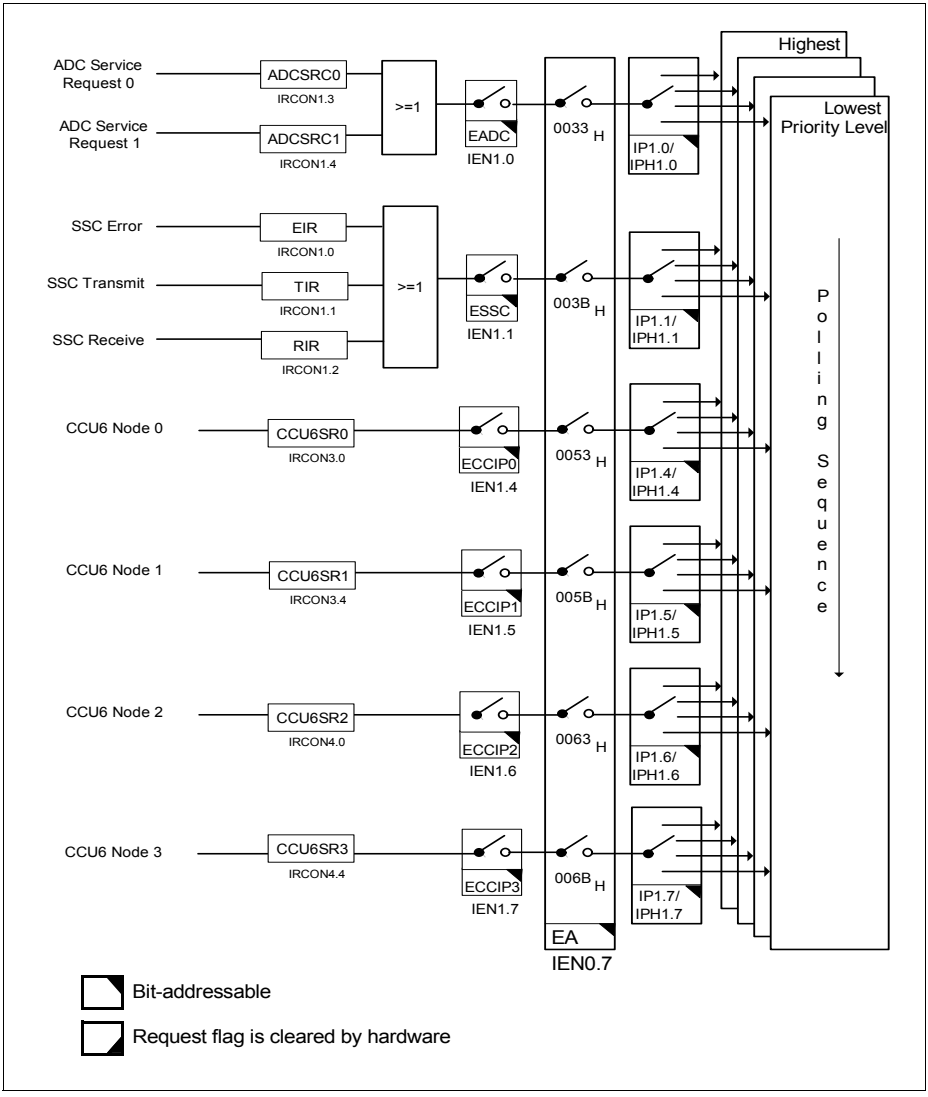


Figure 16 Interrupt Request Sources (Part 3)

3.4.2 Interrupt Source and Vector

Each interrupt source has an associated interrupt vector address. This vector is accessed to service the corresponding interrupt source request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the XC866 interrupt sources to the interrupt vector addresses and the corresponding interrupt source enable bits are summarized in **Table 17**.

Table 17 Interrupt Vector Addresses

Interrupt Source	Vector Address	Assignment for XC866	Enable Bit	SFR
NMI	0073_H	Watchdog Timer NMI	NMIWDT	NMICON
		PLL NMI	NMIPLL	
		Flash NMI	NMIFLASH	
		VDDC Prewarning NMI	NMIVDD	
		VDDP Prewarning NMI	NMIVDDP	
		Flash ECC NMI	NMIECC	
XINTR0	0003_H	External Interrupt 0	EX0	IEN0
XINTR1	$000B_H$	Timer 0	ET0	
XINTR2	0013_H	External Interrupt 1	EX1	
XINTR3	$001B_H$	Timer 1	ET1	
XINTR4	0023_H	UART	ES	
XINTR5	$002B_H$	T2	ET2	
		Fractional Divider (Normal Divider Overflow)		
		LIN		

3.7 Reset Control

The XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC866 is first powered up, the status of certain pins (see **Table 20**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9*V_{DDC}. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* V_{DDC}.

A typical application example is shown in **Figure 21**. V_{DDP} capacitor value is 300 nF. V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the $\overline{\text{RESET}}$ pin should be held low for 500 µs typically. See **Figure 22**.

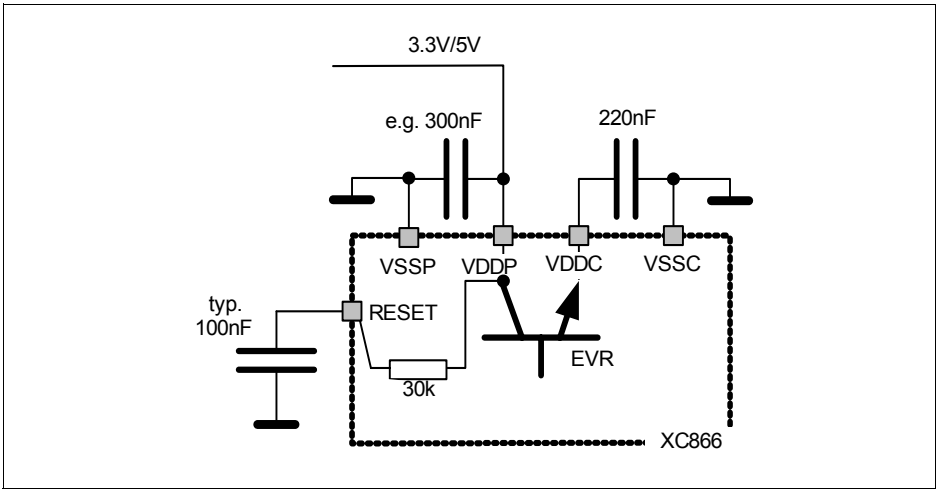


Figure 21 Reset Circuitry

3.8 Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the XC866. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features:

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL.In the XC866, the oscillator can be from either of these two sources: the on-chip oscillator (10 MHz) or the external oscillator (4 MHz to 12 MHz). The term “oscillator” is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default.The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.

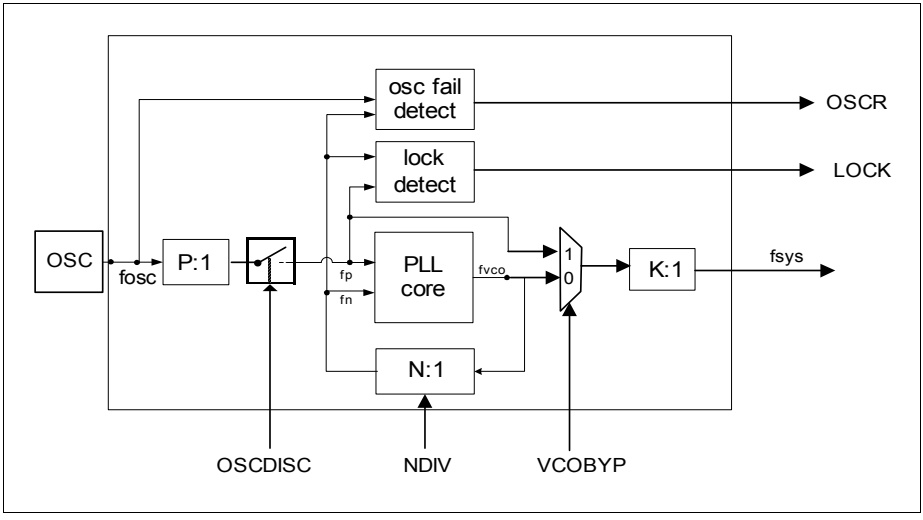
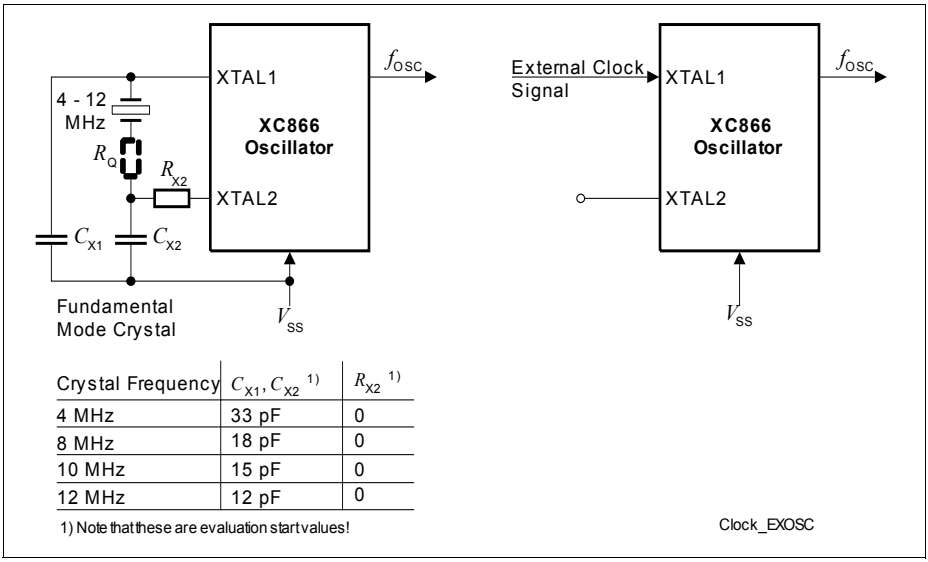


Figure 23 CGU Block Diagram



Crystal Frequency	C_{X1}, C_{X2} 1)	R_{X2} 1)
4 MHz	33 pF	0
8 MHz	18 pF	0
10 MHz	15 pF	0
12 MHz	12 pF	0

1) Note that these are evaluation start values!

Figure 24 External Oscillator Circuitries

Note: For crystal operation, it is strongly recommended to measure the negative resistance in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the minimum and maximum values of the negative resistance specified by the crystal supplier.

Table 24 lists the possible watchdog time range that can be achieved for different module clock frequencies . Some numbers are rounded to 3 significant digits.

Table 24 Watchdog Time Ranges

Reload value in WDTREL	Prescaler for f_{PCLK}	
	2 (WDTIN = 0)	**128 (WDTIN = 1)**
	26.7 MHz	**26.7 MHz**
FF_H	19.2 µs	1.23 ms
$7F_H$	2.48 ms	159 ms
00_H	4.92 ms	315 ms

3.15 Timer 0 and Timer 1

Timers 0 and 1 are count-up timers which are incremented every machine cycle, or in terms of the input clock, every 2 PCLK cycles. They are fully compatible and can be configured in four different operating modes for use in a variety of applications, see **Table 28**. In modes 0, 1 and 2, the two timers operate independently, but in mode 3, their functions are specialized.

Table 28 Timer 0 and Timer 1 Modes

Mode	Operation
0	**13-bit timer** The timer is essentially an 8-bit counter with a divide-by-32 prescaler. This mode is included solely for compatibility with Intel 8048 devices.
1	**16-bit timer** The timer registers, TLx and THx, are concatenated to form a 16-bit counter.
2	**8-bit timer with auto-reload** The timer register TLx is reloaded with a user-defined 8-bit value in THx upon overflow.
3	**Timer 0 operates as two 8-bit timers** The timer registers, TL0 and TH0, operate as two separate 8-bit counters. Timer 1 is halted and retains its count even if enabled.

3.17 Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features:

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

Timer T13 Features:

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features:

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the XC866. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 33 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		min.	max.		
Digital power supply voltage	V_{DDP}	4.5	5.5	V	5V Device
Digital power supply voltage	V_{DDP}	3.0	3.6	V	3.3V Device
Digital ground voltage	V_{SS}	0		V	
Digital core supply voltage	V_{DDC}	2.3	2.7	V	
System Clock Frequency[1)]	f_{SYS}	74	86	MHz	
Ambient temperature	T_A	-40	85	°C	SAF-XC866...
		-40	125	°C	SAK-XC866...

[1)] f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is f_{SYS} / 3. Please refer to **Figure 25** for detailed description.

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions Remarks
			min.	max.		
V_{DDP} = 3.3V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on $\overline{\text{RESET}}$ pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on $\overline{\text{RESET}}$ pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on Port pins	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX}	SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 36 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol	Limit Values			Unit	Test Conditions/ Remarks
		min.	typ .	max.		
Analog reference voltage	V_{AREF} SR	V_{AGND} + 1	V_{DDP}	V_{DDP} + 0.05	V	
Analog reference ground	V_{AGND} SR	V_{SS} - 0.05	V_{SS}	V_{AREF} - 1	V	
Analog input voltage range	V_{AIN} SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}	–	20	40	MHz	module clock
	f_{ADCI}	–	–	10	MHz	internal analog clock See **Figure 33**
Sample time	t_S CC	(2 + INPCR0.STC) × t_{ADCI}			µs	
Conversion time	t_C CC	See **Section 4.2.3.1**			µs	
Total unadjusted error	TUE[1] CC	–	–	±1	LSB	8-bit conversion.[2]
		–	–	±2	LSB	10-bit conversion.
Differential Nonlinearity	DNL CC	–	±1	–	LSB	10-bit conversion[2]
Integral Nonlinearity	INL CC	–	±1	–	LSB	10-bit conversion[2]
Offset	OFF CC	–	±1	–	LSB	10-bit conversion[2]
Gain	GAIN CC	–	±1	–	LSB	10-bit conversion[2]
Switched capacitance at the reference voltage input	C_{AREFSW} CC	–	10	20	pF	[2][3]

Table 45 JTAG Timing (Operating Conditions apply; C_L = 50 pF)

Parameter	Symbol		Limits		Unit
			min	max	
TMS setup to TCK ↑	t_1	SR	8.0	–	ns
TMS hold to TCK ↑	t_2	SR	5.0	–	ns
TDI setup to TCK ↑	t_1	SR	11.0	–	ns
TDI hold to TCK ↑	t_2	SR	6.0	–	ns
TDO valid output from TCK ↓	t_3	CC	–	23	ns
TDO high impedance to valid output from TCK ↓	t_4	CC	–	26	ns
TDO valid output to high impedance from TCK ↓	t_5	CC	–	18	ns

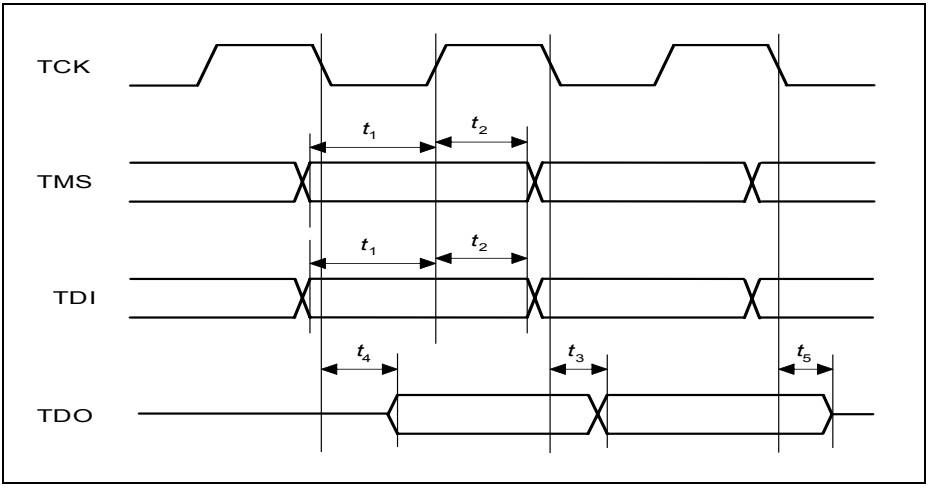


Figure 44 JTAG Timing